SPECIFICATION

CUSTOMER：

PRODUCT ： 声表谐振器

MODEL NO： LT-SR-433-F11

PREPARED： 杨嘉妮 CHECKED： 顾杰

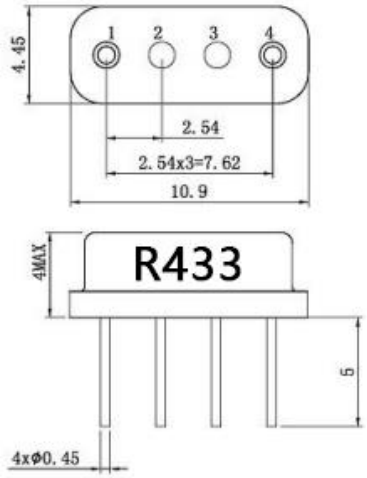
D A T E： 2022-03-10

CUSTOMER RECEIVED:		
CHECKED	APPROVED	DATE

版本说明

日期	版本号	修订说明	拟制	审核
2022-03-10	1.0	初版	杨嘉妮	顾杰

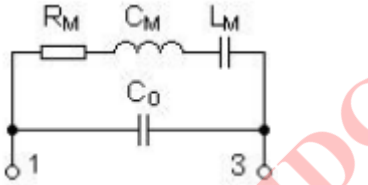
1. Package Dimension (F-11)

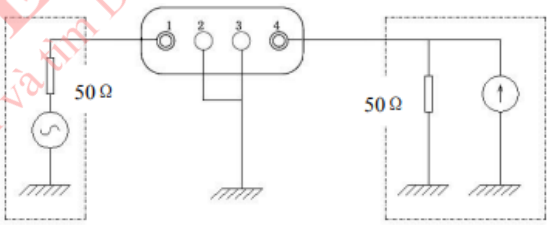


Pin	Connection
1	Input/ Output
2,3	Case Ground
4	Output/ Input

Marking	
R	SAW resonator
R433	Center Frequency

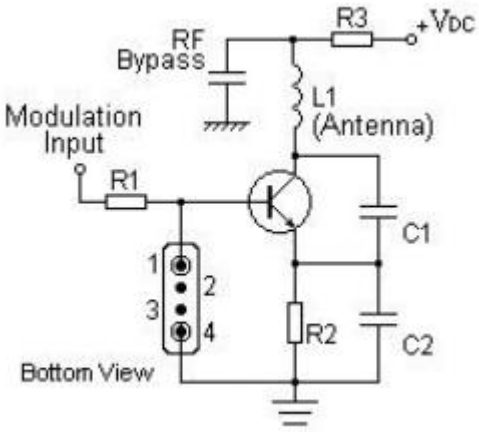
2. Equivalent LC Model and Test Circuit



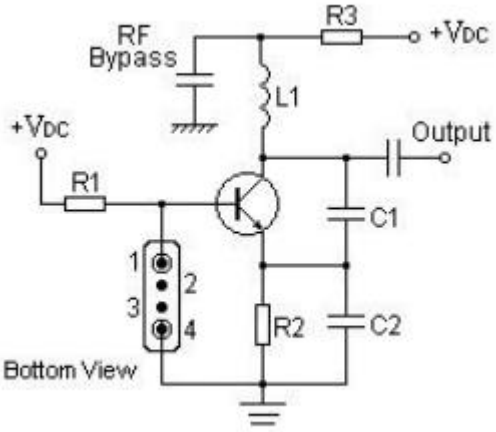


3.Typical Application Circuit

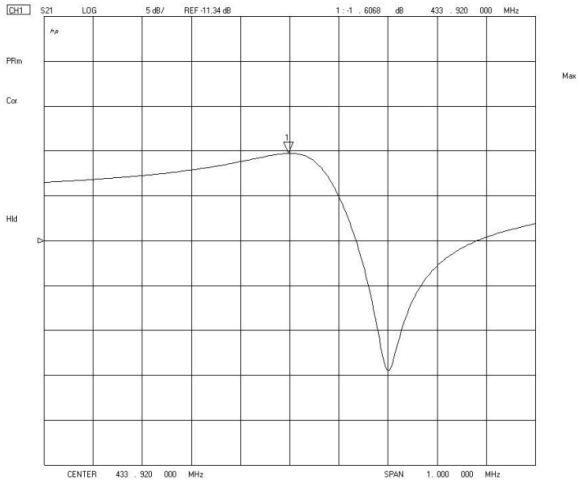
1) Typical Low-Power Transmitter Application



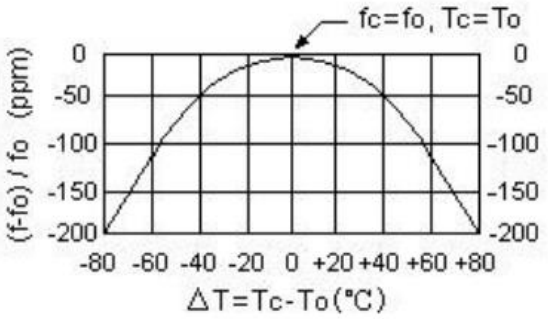
2) Typical Local Oscillator Application



4. Typical Frequency Response



5.Temperature Characteristics



6. Performance

6-1.Maximum Rating

Rating	Value	Units
CW RF Power Dissipation	+10	dBm
DC Voltage Between Any Two Pins	+10V	VDC
Operation Temperature	-40 to +85	℃
Storage Temperature	-55 to +125	℃

6-2.Electronic Characteristics

Characteristic		Sym	Minimum	Typical	Maximum	Units
Center Frequency (+25℃)	Absolute Frequency	f_C		433.92		MHz
	Tolerance from433.92MHz	$\triangle f_C$		±75		kHz
Insertion Loss		IL		1.4	2.0	dB
Quality Factor	Unloaded Q	Q_U		14215		
	50 Ω Loaded Q	Q_L		1791		
Temperature Stability	Turnover Temperature	T_O	10	25	40	℃
	Turnover Frequency	f_O		fc		kHz
	Frequency Temperature Coefficient	FTC		0.032		ppm/℃^{2}
Frequency Aging Absolute Value during the First Year		$\|f_A\|$		≤10		ppm/yr
DC Insulation Resistance Between Any Two Pins			1.0			MΩ
RF Equivalent RLC Model	Motional Resistance	R_M		15	26	Ω
	Motional Inductance	L_M		98.9		μH
	Motional Capacitance	C_M		2.35		fF
	Pin 1 to Pin 3 Static Capacitance	C_O	2.8	3.1	3.4	pF

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling!

Notes:

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to ESD protect in the test.
2. Static voltage between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may be soldered. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and matching network. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.